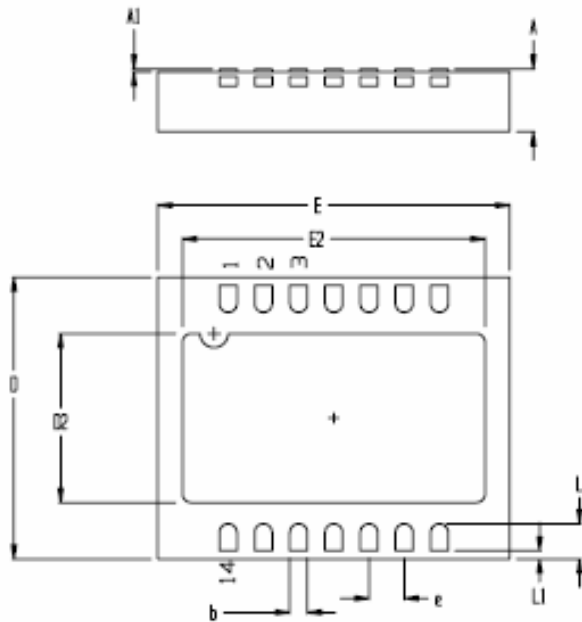
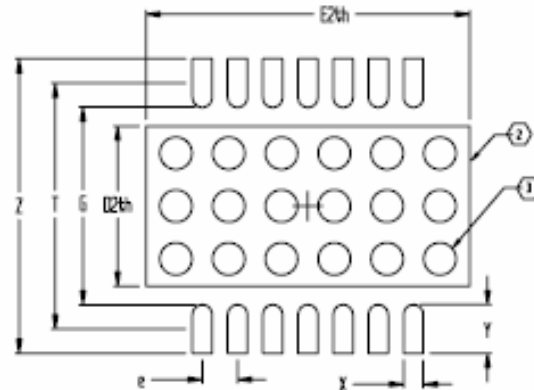


REVISIONS

REV	DESCRIPTION	CHANGED BY	DATE
A	CHANGED NOTE 3 PER EEM 51305	RH	12.JAN04



BOTTOM VIEW



RECOMMENDED PAD LAYOUT
TOP VIEW

SYMBOL	MIN.	NOM.	MAX.
A	0.90	0.95	1.00
A1	0.00	0.01	0.05
A3		0.20 REF.	
b	0.20	0.25	0.30
D2		0.50 BSC	
L	0.45	0.50	0.65
D		4.00 BSC	
E		5.00 BSC	
D2	2.25	2.40	2.55
E2	4.15	4.30	4.45
L1	-	-	.15
Z		4.180 BSC	
G		2.800 BSC	
X		0.280 BSC	
Y		0.690 BSC	
D2th		2.273 BSC	
E2th		4.600 BSC	
T		3.490 BSC	

NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL DIMS ARE IN MM.
- ② SOLID THERMAL PAD 100% VOID OF SOLDER MASK.
- ③ SOLDER PASTE:
 - PERIMETER PADS TO BE 1:1 TO PCB LAND PADS.
 - THERMAL PAD OPENING MUST GIVE 50 TO 80% COVERAGE.
 - PATTERN SHOWN GIVES APPROXIMATELY 80% COVERAGE USING SOLDER PASTE DOTS 0.46 DIA ON 0.75 PITCH 19EA.
 - TEMPLATE SHOULD BE LASER CUT AND ELECTRO POLISHED.
4. SOLDER MASK SHOULD BE CUT BACK 0.06 FROM ALL LAND PATTERNS.
5. FOR MORE DETAILS SEE ANKOR'S APPLICATION NOTES FOR SURFACE MOUNT ASSEMBLY OF ANKOR'S MICROLEADFRAME (MLF) PACKAGES.

14 pin 4 mm x 5 mm MLF™ (MicroLeadFrame™)